

2.2mA, 11MHz, Low Noise, Rail-to-Rail I/O Tiny Package, CMOS Operational Amplifier

GENERAL DESCRIPTION

The SGM8600 is a dual, low voltage, low noise and low power operational amplifier, which can operate from 2.1V to 5.5V single supply, while consuming only 2.2mA quiescent current at 5V.

The minimum input common mode voltage is within 0.1V below the negative rail, and the output swing is rail-to-rail with heavy loads. The SGM8600 features a 4mV maximum input offset voltage. The SGM8600 exhibits a high gain-bandwidth product of 11MHz and a slew rate of 8.5V/µs. These specifications make the operational amplifier appropriate for various applications.

The SGM8600 is available in Green SOIC-8 and TDFN-2×2-8L packages. It is specified over the extended -40°C to +125°C industrial temperature range.

FEATURES

Offset Voltage Range: 0mV to 4mV
 High Gain-Bandwidth Product: 11MHz

• High Slew Rate: 8.5V/µs

• Settling Time to 0.1% with 2V Step: 0.21µs

SGM8600

Overload Recovery Time: 0.6µs
 Low Noise: 8.5nV/√Hz at 10kHz

• Rail-to-Rail Input and Output

• Supply Voltage Range: 2.1V to 5.5V

• Input Common Mode Voltage Range:

-0.1V to 5.6V with $V_S = 5.5V$

• Low Power: 2.2mA (TYP) Supply Current

• -40°C to +125°C Operating Temperature Range

 Available in Green SOIC-8 and TDFN-2×2-8L Packages

APPLICATIONS

Sensors

Audio

Active Filters

A/D Converters

Communications

Test Equipment

Cellular and Cordless Phones

Laptops and PDAs

Photodiode Amplification

Battery-Powered Instrumentation

PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGM8600	SOIC-8	-40°C to +125°C	SGM8600XS8G/TR	SGM 8600XS8 XXXXX	Tape and Reel, 2500
3GW0000	TDFN-2×2-8L	-40°C to +125°C	SGM8600XTDE8G/TR	8600 XXXX	Tape and Reel, 3000

MARKING INFORMATION

NOTE: XXXX = Date Code. XXXXX = Date Code and Vendor Code.

TDFN-2×2-8L

XXXX

Date Code - Week

Date Code - Week

Date Code - Year

Date Code - Year

Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS

Supply Voltage, +V _S to -V _S	6V
Input Common Mode Voltage Range	
(-V _S) - 0.3V to (+V _S)	+ 0.3
Junction Temperature+1	50°C
Storage Temperature Range65°C to +1	50°C
Lead Temperature (Soldering, 10s)+2	60°C
ESD Susceptibility	
HBM80	V00C
MM	100V
CDM	V00C

RECOMMENDED OPERATING CONDITIONS

Input Voltage Range	2.1V to 5.5V
Operating Temperature Range	40°C to +125°C

OVERSTRESS CAUTION

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

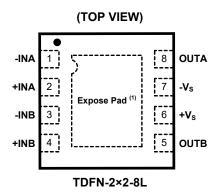
ESD SENSITIVITY CAUTION

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

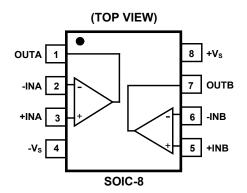
DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

PIN CONFIGURATIONS



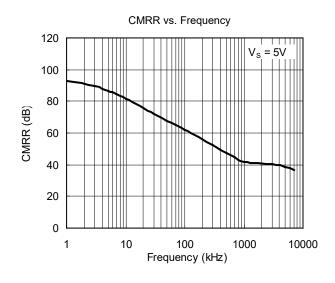
NOTE 1: Exposed pad can be connected to -V_S or left floating.

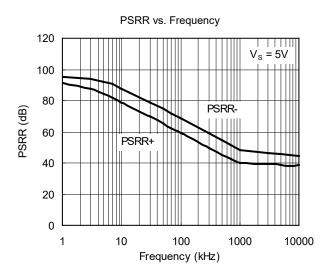


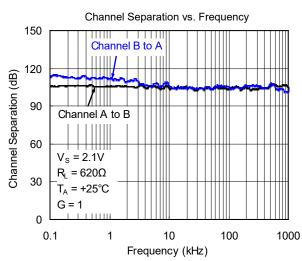
ELECTRICAL CHARACTERISTICS

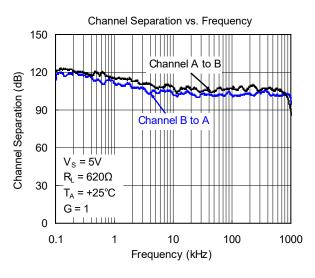
				SGM8600						
DADAMETED	CONDITIONS	TYP	MIN/MAX OVER TEMPERATURE							
PARAMETER	CONDITIONS	+25℃	+25℃	-40°C to +85°C	-40℃ to +125℃	UNITS	MIN/ MAX			
Input Characteristics										
Input Offset Voltage (Vos)			0			mV	MIN			
input Offset voltage (vos)		2	4	4.5	5	mV	MAX			
Input Bias Current (I _B)		1				pА	TYP			
Input Offset Current (Ios)		1				pА	TYP			
Input Common Mode Voltage Range (V _{CM})	V _S = 5.5V	-0.1 to +5.6				V	TYP			
Common Mode Rejection Ratio (CMRR)	$V_S = 5.5V$, $V_{CM} = -0.1V$ to 4V	82	67	66	65	dB	MIN			
Common Mode Rejection Ratio (CMRR)	$V_S = 5.5V$, $V_{CM} = -0.1V$ to 5.6V	70	59	58	57	dB	MIN			
Open-Loop Voltage Gain (A _{OL})	$R_L = 600\Omega$, $V_{OUT} = 0.15V$ to 4.85V	92	84	74	65	dB	MIN			
Open-Loop Voltage Gain (A _{OL})	$R_L = 10k\Omega$, $V_{OUT} = 0.05V$ to 4.95V	105	96	87	72	dB	MIN			
Input Offset Voltage Drift ($\Delta V_{OS}/\Delta_T$)		8.7				μν/°C	TYP			
Output Characteristics										
Output Valtage Suing from Deil	$R_L = 600\Omega$	76	90	110	135	mV	MAX			
Output Voltage Swing from Rail	$R_L = 10k\Omega$	7	11	13	18	mV	MAX			
Output Current (I _{OUT})		63	50	41	36	mA	MIN			
Closed-Loop Output Impedance	f = 1MHz, G = 1	8.5				Ω	TYP			
Power Supply										
On a realism at Maltanaa Danasa		2.1	2.1	2.1	2.1	V	MIN			
Operating Voltage Range		5.5	5.5	5.5	5.5	V	MAX			
Power Supply Rejection Ratio (PSRR)	$V_S = +2.1V \text{ to } +5.5V,$ $V_{CM} = (-V_S) + 0.5V$	79	69	68	64	dB	MIN			
Quiescent Current (I _Q)	I _{OUT} = 0	2.2	2.7	3	3.5	mA	MAX			
Dynamic Performance						•				
Gain-Bandwidth Product (GBP)	$R_L = 10k\Omega$	11				MHz	TYP			
Phase Margin (φ _O)		62				0	TYP			
Full Power Bandwidth (BW _P)	< 1% distortion	400				kHz	TYP			
Slew Rate (SR)	G = 1, 2V output step	8.5				V/µs	TYP			
Settling Time to 0.1% (t _S)	G = 1, 2V output step	0.21				μs	TYP			
Overload Recovery Time	$V_{IN} \times G = V_{S}$	0.6				μs	TYP			
Noise Performance	•									
	f = 1kHz	12.5				nV/√Hz	TYP			
Input Voltage Noise Density (en)	f = 10kHz	8.5				nV/√Hz	TYP			

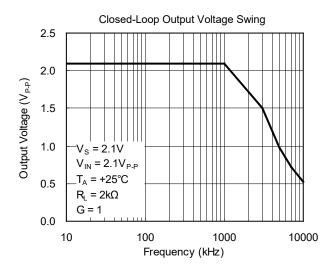
TYPICAL PERFORMANCE CHARACTERISTICS

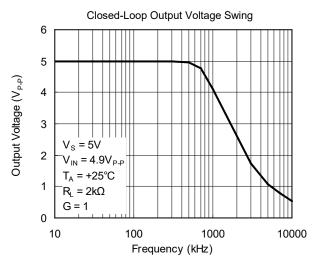




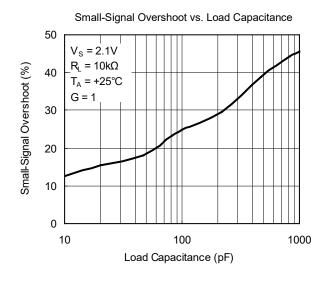


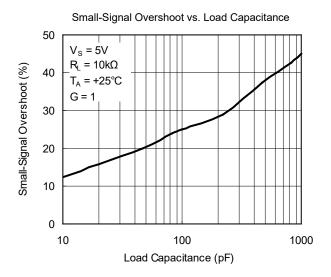


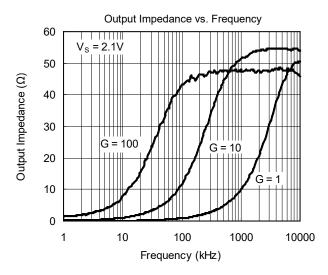


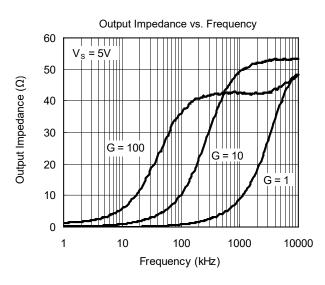


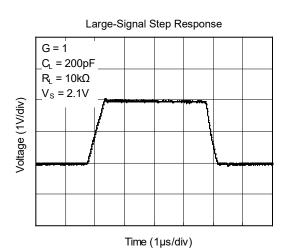
TYPICAL PERFORMANCE CHARACTERISTICS (continued)

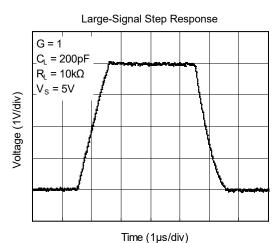




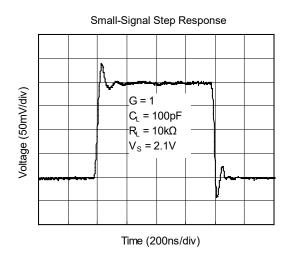


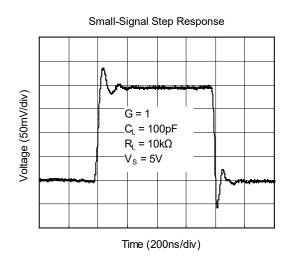


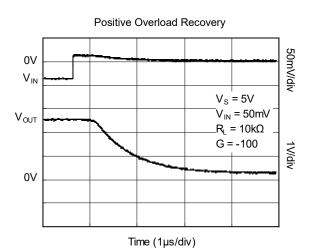


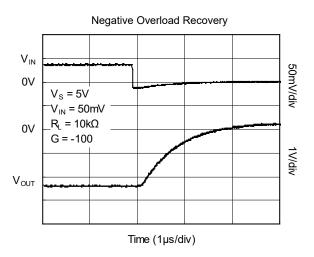


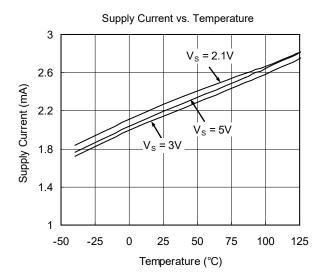
TYPICAL PERFORMANCE CHARACTERISTICS (continued)

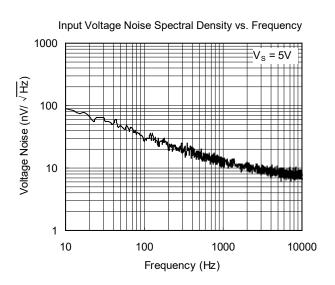




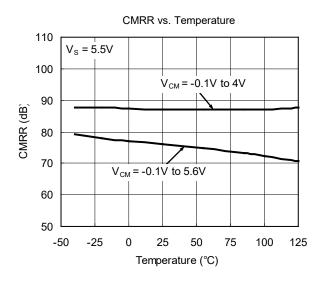


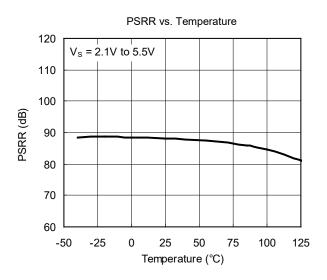


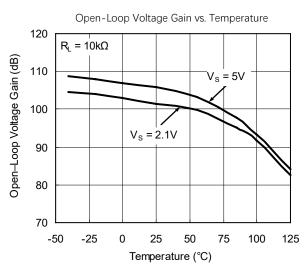


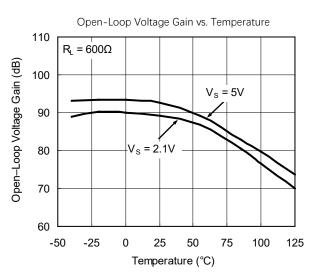


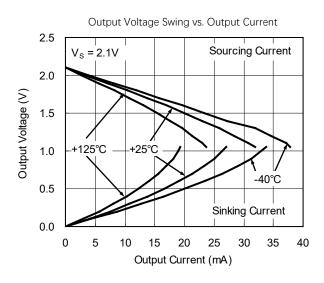
TYPICAL PERFORMANCE CHARACTERISTICS (continued)

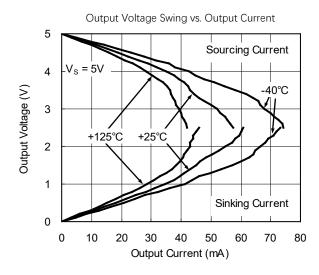












APPLICATION INFORMATION

Rail-to-Rail Input

When SGM8600 works at the power supply between 2.1V and 5.5V, the input common mode voltage range is from $(-V_S)$ - 0.1V to $(+V_S)$ + 0.1V. In Figure 1, the ESD diodes between the inputs and the power supply rails will clamp the input voltage not to exceed the rails.

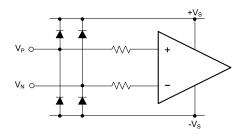


Figure 1. Input Equivalent Circuit

Rail-to-Rail Output

The SGM8600 supports rail-to-rail output operation. In single power supply application, for example, when +V_S = 5V, -V_S = GND, $10k\Omega$ load resistor is tied from OUT pin to ground, the typical output swing range is from 0.007V to 4.993V.

Driving Capacitive Loads

The SGM8600 is designed for unity-gain stable for capacitive load up to 4700pF. If greater capacitive load must be driven in application, the circuit in Figure 2 can be used. In this circuit, the IR drop voltage generated by $R_{\rm ISO}$ is compensated by feedback loop.

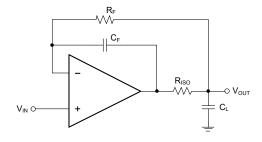


Figure 2. Circuit to Drive Heavy Capacitive Load

Power Supply Decoupling and Layout

A clean and low noise power supply is very important in amplifier circuit design, besides of input signal noise, the power supply is one of important source of noise to the amplifier through $+V_S$ and $-V_S$ pins. Power supply bypassing is an effective method to clear up the noise at power supply, and the low impedance path to ground of decoupling capacitor will bypass the noise to GND. In application, $10\mu F$ ceramic capacitor paralleled with $0.1\mu F$ or $0.01\mu F$ ceramic capacitor is used in Figure 3. The ceramic capacitors should be placed as close as possible to $+V_S$ and $-V_S$ power supply pins.

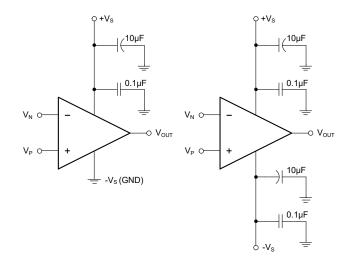


Figure 3. Amplifier Power Supply Bypassing

Grounding

In low speed application, one node grounding technique is the simplest and most effective method to eliminate the noise generated by grounding. In high speed application, the general method to eliminate noise is to use a complete ground plane technique, and the whole ground plane will help distribute heat and reduce EMI noise pickup.

Reduce Input-to-Output Coupling

To reduce the input-to-output coupling, the input traces must be placed as far away from the power supply or output traces as possible. The sensitive trace must not be placed in parallel with the noisy trace in same layer. They must be placed perpendicularly in different layers to reduce the crosstalk. These PCB layout techniques will help to reduce unwanted positive feedback and noise.

APPLICATION INFORMATION (continued)

Typical Application Circuits

Difference Amplifier

The circuit in Figure 4 is a design example of classical difference amplifier. If $R_4/R_3 = R_2/R_1$, then $V_{OUT} = (V_P - V_N) \times R_2/R_1 + V_{REF}$.

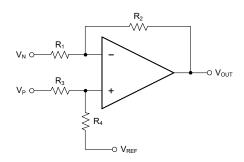


Figure 4. Difference Amplifier

High Input Impedance Difference Amplifier

The circuit in Figure 5 is a design example of high input impedance difference amplifier, the added amplifiers at the input are used to increase the input impedance and eliminate drawback of low input impedance in Figure 4.

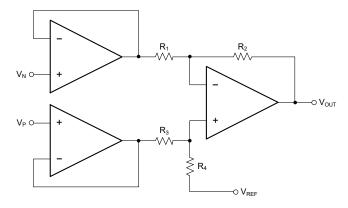


Figure 5. High Input Impedance Difference Amplifier

Active Low-Pass Filter

The circuit in Figure 6 is a design example of active low-pass filter, the DC gain is equal to $-R_2/R_1$ and the -3dB corner frequency is equal to $1/2\pi R_2C$. In this design, the filter bandwidth must be less than the bandwidth of the amplifier, the resistor values must be selected as low as possible to reduce ringing or oscillation generated by the parasitic parameters in PCB layout.

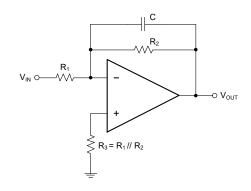


Figure 6. Active Low-Pass Filter

2.2mA, 11MHz, Low Noise, Rail-to-Rail I/O Tiny Package, CMOS Operational Amplifier

SGM8600

REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

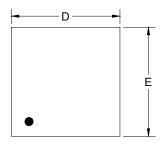
Changes from Original (SEPTEMBER 2015) to REV.A

Page

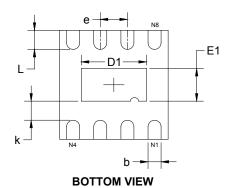
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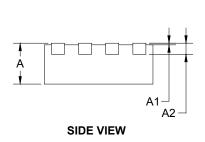


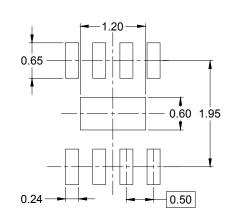
PACKAGE OUTLINE DIMENSIONS TDFN-2×2-8L



TOP VIEW



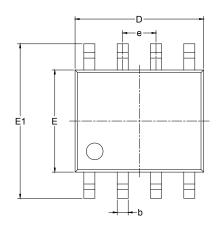


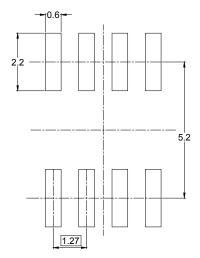


RECOMMENDED LAND PATTERN (Unit: mm)

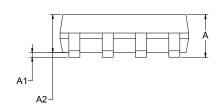
Symbol	_	nsions meters	Dimensions In Inches			
	MIN	MAX	MIN	MAX		
Α	0.700	0.800	0.028	0.031		
A1	0.000	0.050	0.000	0.002		
A2	0.203	REF	0.008 REF			
D	1.900	2.100	0.075	0.083		
D1	1.100	1.300	0.043	0.051		
E	1.900	2.100	0.075	0.083		
E1	0.500	0.700	0.020	0.028		
k	k 0.200 MIN		0.200 MIN		0.008	3 MIN
b	0.180	0.300	0.007	0.012		
е	0.500) TYP	0.020	TYP		
L	0.250	0.450	0.010 0.018			

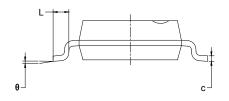
PACKAGE OUTLINE DIMENSIONS SOIC-8





RECOMMENDED LAND PATTERN (Unit: mm)

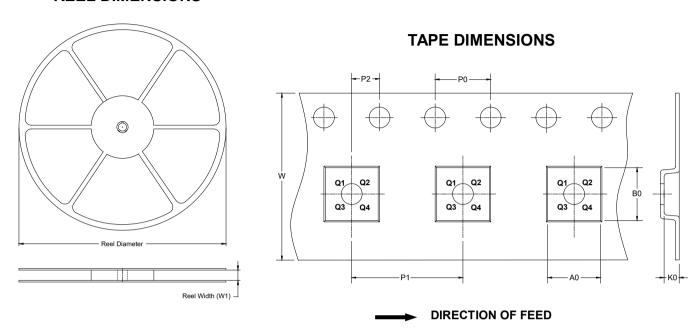




Symbol		nsions meters	Dimensions In Inches		
,	MIN	MAX	MIN	MAX	
Α	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
Е	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.27 BSC		0.050	BSC	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	

TAPE AND REEL INFORMATION

REEL DIMENSIONS

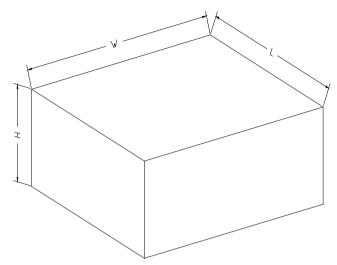


NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TDFN-2×2-8L	7"	9.5	2.30	2.30	1.10	4.0	4.0	2.0	8.0	Q1
SOIC-8	13"	12.4	6.40	5.40	2.10	4.0	8.0	2.0	12.0	Q1

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
7" (Option)	368	227	224	8
7"	442	410	224	18
13"	386	280	370	5